



AI-Driven Innovation in Optoelectrical Packaging

AI驱动光电封装创新

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MRSI
MYCRONIC

Innovative packaging solutions to meet the rapidly growing demands of the AI industry



Tewksbury, USA



Shenzhen, China

Latest Innovation



Active Aligner



1 micron

High Force

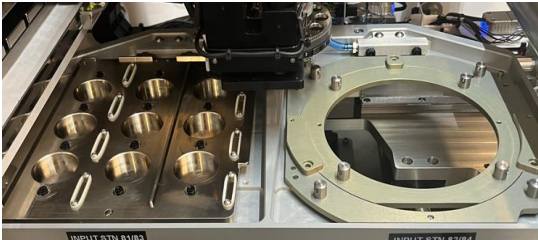


High Speed

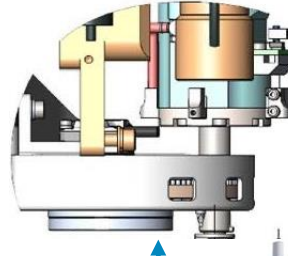
- MRSI is a part of Mycronic Group, Sweden owned company
- Founded in MA, USA in 1984, have entities in both USA & China
- Provide ultra-high precision die bonder, dispenser and AA equipment
- Main market: Photonics industry, Defense & Air Space
- Global sales and service, demo centers in USA & China

MRSI Flexible High-precision, Multi-die Bonding Solutions

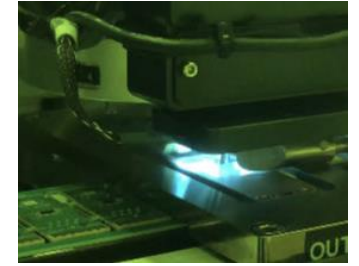
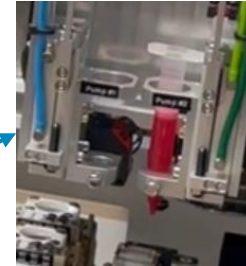
Waffle Pack/Gel-Pak & 8" wafer ring



Gantry head with **patented** tool changer-12 tips



Epoxy dispensing + UV Curing



Conveyor



Eutectic Stage

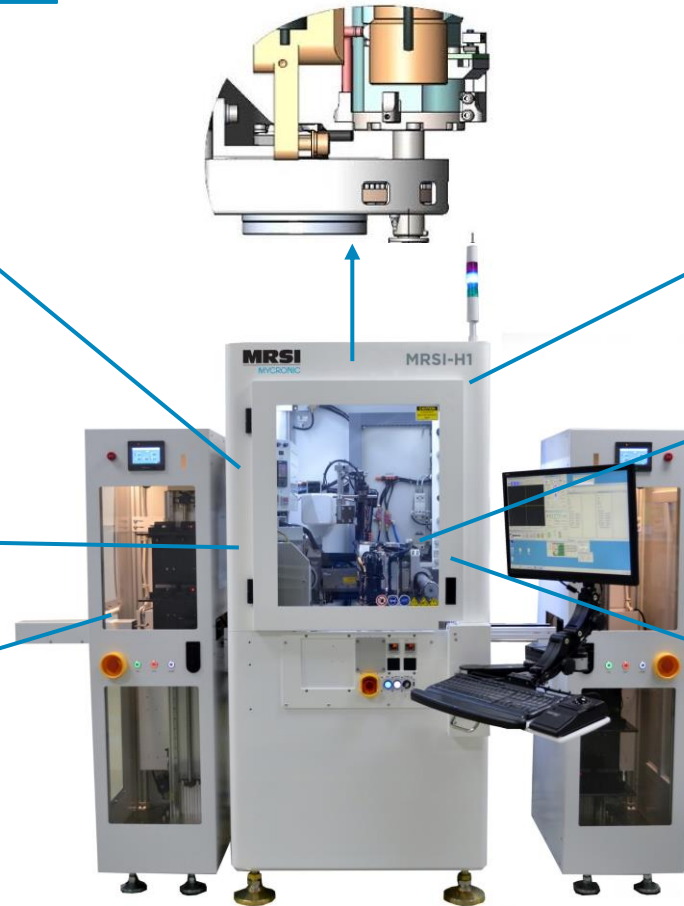


Stamp well



Cassette Loader/Unloader

Flip chip bonding

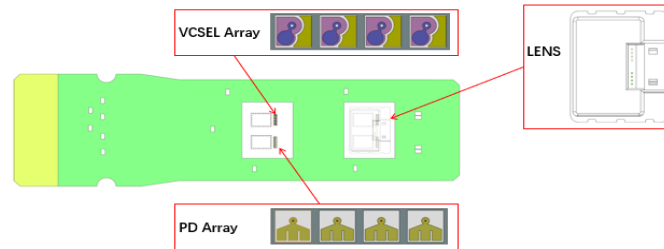


GaAs Based AI Transceivers Assembling Results

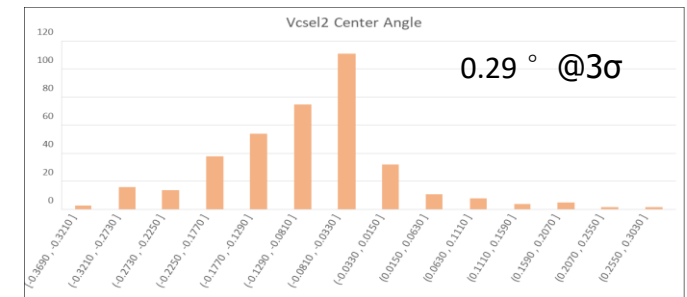
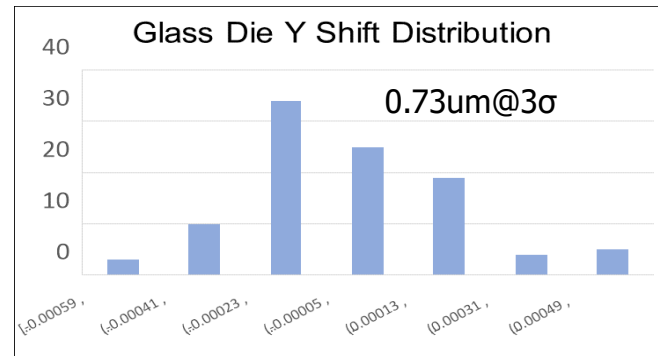
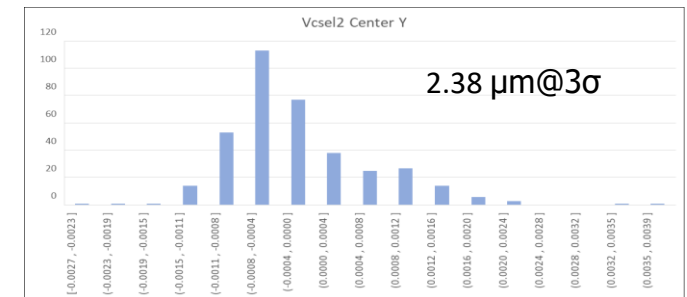
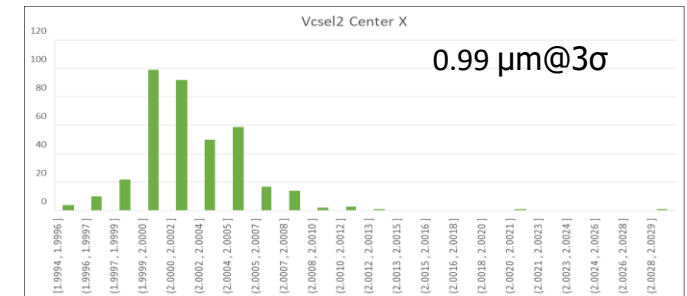
MRSI-LEAP achieved $< \pm 2.5 \mu\text{m}$ epoxy process post bonding accuracy



MRSI-LEAP



375 pcs AOC production data

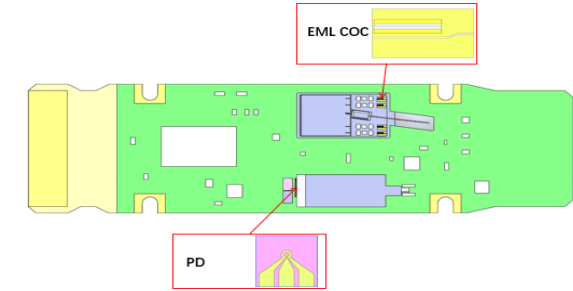
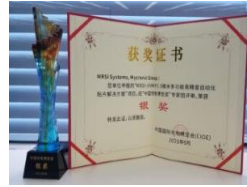


InP Based AI Transceivers Assembling Results

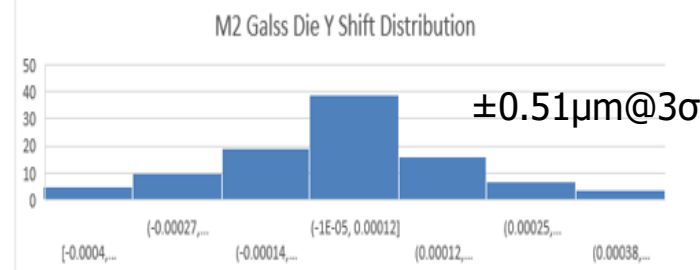
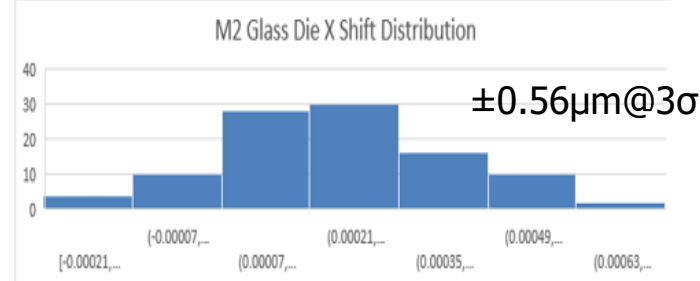
MRSI-HVM achieved $< \pm 2.5 \mu\text{m}$ eutectic process post bonding accuracy



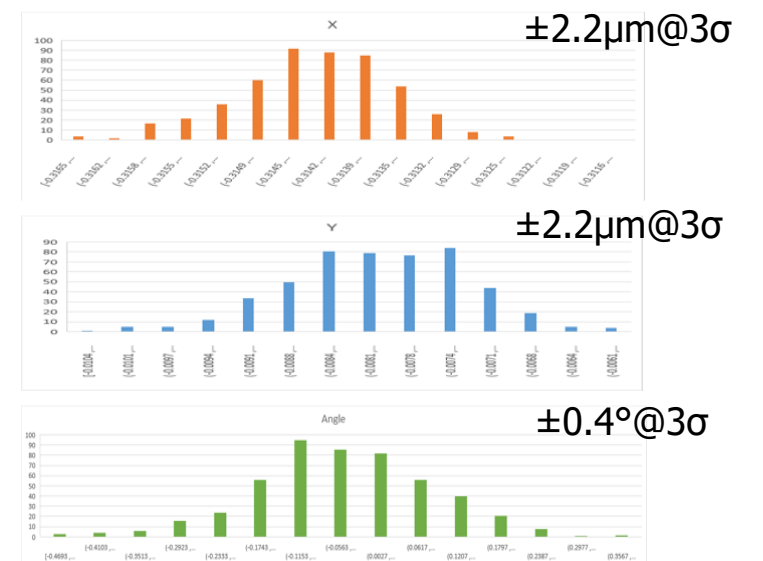
MRSI-HVM1



100 Glass Dies Test Results



500 CoC Production Results



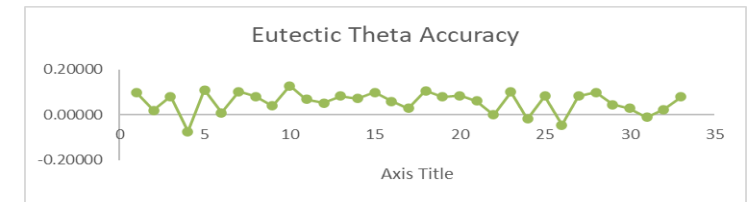
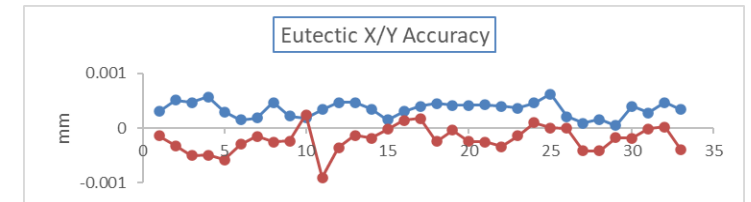
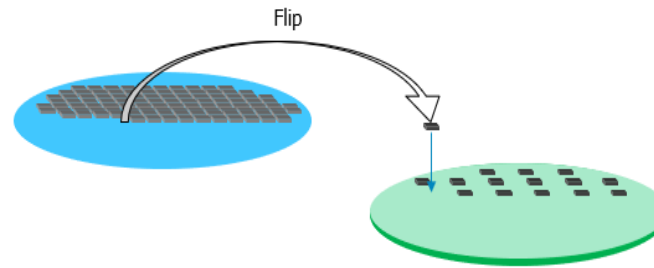
Wafer-level Packaging For SiPh LAB Process Results

LAB process have short process time to prevent double reflow



MRSI-S-HVM
Auto-switched dual-accuracy
Die Bonder

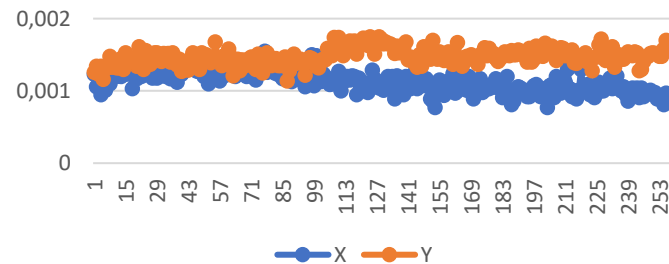
High Density & Wafer Level LAB Eutectic



LAB Eutectic post bonding results

Averages	X	Y	T
MIN	0.000050	-0.000900	-0.073000
MAX	0.000620	0.000250	0.129000
ave	0.000347	-0.000202	0.056758
Range	0.000570	0.001150	0.202000
stdev	0.000141	0.000238	0.047531
3*stdev	0.000423	0.000713	0.142593

Glass die with NFC



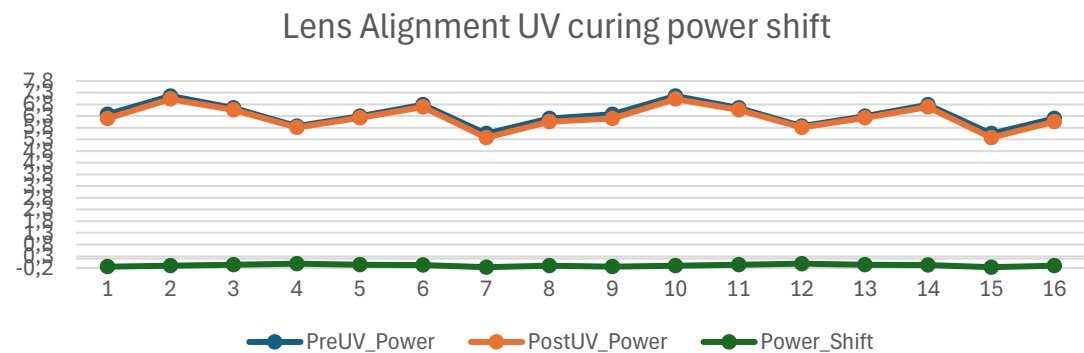
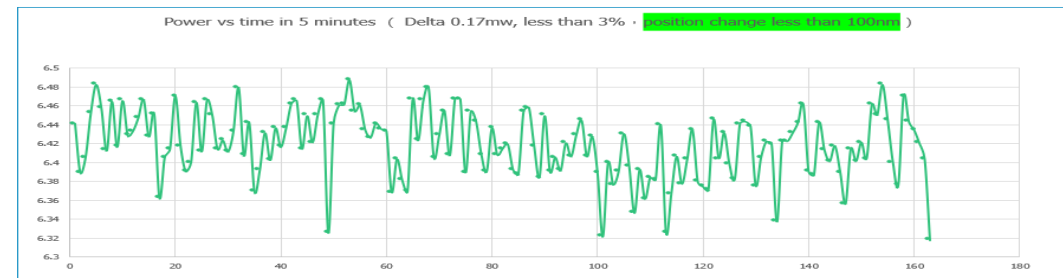
X=0.44µm@3σ Y=0.34µm@3σ

AI Transceivers Lens Active Alignment Coupling Results

High-flexibility, high-precision, high-speed and high-reliability active aligner



MRSI-A-L



Q&A



THANK YOU!



CIOE Booth No.10B79



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Bringing tomorrow's electronics to life